L Number	Hits	Search Text	DB	Time stamp
1	2582466	die chip dice semiconductor miicroelectronic ic (integrated adj	USPAT; US-PGPUB;	2004/08/31 05:09
	0.05.000	circuit)	EPO; JPO; DERWENT; IBM_TDB	
2	805082	<pre>(((printed wiring circuit) adj5 board) carrier substrate board pcb support) same (die chip dice semiconductor miicroelectronic ic (integrated adj circuit))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/31
3	162024	((((printed wiring circuit) adj5 board) carrier substrate board pcb support) same (die chip dice semiconductor microelectronic ic (integrated adj circuit))) same (stack stacked stacking mounted mounting mount stackable mount mounted mounting mountable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:13
4	36617	<pre>(((((printed wiring circuit) adj5 board) carrier substrate board pcb support) same (die chip dice semiconductor microelectronic ic (integrated adj circuit))) same (stack stacked stacking mounted mounting mount stackable mount mounted mounting mountable)) AND (ball bump flipchip (flip adj3 (chip die)))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:14
5	17360	<pre>((((((printed wiring circuit) adj5 board) carrier substrate board pcb support) same (die chip dice semiconductor miicroelectronic ic (integrated adj circuit))) same (stack stacked stacking mounted mounting mount stackable mount mounted mounting mountable)) AND (ball bump flipchip (flip adj3 (chip die))))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:15
6	12911	and (lead leadframe (lead adj frame) loc) (package packaging packaged) and (((((((printed wiring circuit) adj5 board) carrier substrate board pcb support) same (die chip dice semiconductor miicroelectronic ic (integrated adj circuit))) same (stack stacked stacking mounted mounting mount stackable mount mounted mounting mountable)) AND (ball bump flipchip (flip adj3 (chip die)))) and (lead leadframe (lead adj frame) loc))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:20
7	2504	257/777	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/31 05:20
8	3726	257/723	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/31 05:20
9	4071	257/778	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/08/31 05:20
10	2736	257/686	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/31 05:21

	·			1 0 0 0 1 0 0 1 = -
11	5342	257/666	USPAT;	2004/08/31
			US-PGPUB;	05:21
			EPO; JPO;	
			DERWENT;	
		l /	IBM_TDB	
12	1029	257/679	USPAT;	2004/08/31
			US-PGPUB;	05:21
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
13	1182	257/685	USPAT;	2004/08/31
			US-PGPUB;	05:21
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
14	805	257/673	USPAT;	2004/08/31
			US-PGPUB;	05:21
			EPO; JPO;	
			DERWENT;	
		,	IBM TDB	
15	2069	257/734	USPAT;	2004/08/31
			US-PGPUB;	05:22
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
16	3317	257/737	USPAT;	2004/08/31
-	,		US-PGPUB;	05:22
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
17	2758	257/738	USPAT;	2004/08/31
	2,30	20,7,00	US-PGPUB;	05:22
			EPO; JPO;	00.22
			DERWENT;	
			IBM TDB	
18	17486	257/777 257/723 257/778 257/686 257/666	USPAT;	2004/08/31
10	1/400	257/679 257/685 257/673 257/734 257/737	US-PGPUB;	05:22
		257/738	1	05.22
		201,130	EPO; JPO;	
			DERWENT;	
19	4276	(/nackage nackaging nackaged) and	IBM_TDB	2004/08/21
12	42/6	((package packaging packaged) and	USPAT;	2004/08/31
		(((((((printed wiring circuit) adj5	US-PGPUB;	05:24
		board) carrier substrate board pcb	EPO; JPO;	
		support) same (die chip dice	DERWENT;	
		semiconductor microelectronic ic	IBM_TDB	
		(integrated adj circuit))) same (stack		
		stacked stacking mounted mounting mount		
		stackable mount mounted mounting		
		mountable)) AND (ball bump flipchip (flip		
		adj3 (chip die)))) and (lead leadframe		
		(lead adj frame) loc))) and (257/777		
		257/723 257/778 257/686 257/666 257/679		
	_	257/685 257/673 257/734 257/737 257/738)		
20	3361	(((package packaging packaged) and	USPAT;	2004/08/31
		((((((printed wiring circuit) adj5	US-PGPUB;	05:25
		board) carrier substrate board pcb	EPO; JPO;	
		support) same (die chip dice	DERWENT;	
]		semiconductor miicroelectronic ic	IBM TDB	
1		(integrated adj circuit))) same (stack	_	
		stacked stacking mounted mounting mount		
		stackable mount mounted mounting		
		mountable)) AND (ball bump flipchip (flip		
		adj3 (chip die)))) and (lead leadframe		
1		(lead adj frame) loc))) and (257/777		
		257/723 257/778 257/686 257/666 257/679		
		257/685 257/673 257/734 257/737 257/738))		
		and (different difference)		
· · · · · · · · · · · · · · · · · · ·	i		L	L

		,		2004/00/04
21	2199	<pre>((((package packaging packaged) and ((((((printed wiring circuit) adj5</pre>	USPAT; US-PGPUB;	2004/08/31 05:27
		board) carrier substrate board pcb	EPO; JPO;	03.27
		support) same (die chip dice	DERWENT;	
		semiconductor microelectronic ic	IBM_TDB	
		(integrated adj circuit))) same (stack stacked stacking mounted mounting mount		
		stackable mount mounted mounting		
		mountable)) AND (ball bump flipchip (flip		
		adj3 (chip die)))) and (lead leadframe (lead adj frame) loc))) and (257/777		
		257/723 257/778 257/686 257/666 257/679		
		257/685 257/673 257/734 257/737 257/738))		
	ļ	and (different difference)) and		
		(encapsulating encapsulated encapsulation encapsulant mold molded encased encase		
		encasing)		
22	1946	solder and ((((package packaging	USPAT;	2004/08/31
		<pre>packaged) and ((((((printed wiring circuit) adj5 board) carrier substrate</pre>	US-PGPUB; EPO; JPO;	05:28
		board pcb support) same (die chip dice	DERWENT;	
		semiconductor miicroelectronic ic	IBM_TDB	
		(integrated adj circuit))) same (stack		
		stacked stacking mounted mounting mount stackable mount mounted mounting		
		mountable)) AND (ball bump flipchip (flip		
		adj3 (chip die)))) and (lead leadframe		
		(lead adj frame) loc))) and (257/777 257/723 257/778 257/686 257/666 257/679		
	1	257/685 257/673 257/734 257/737 257/738))		
		and (different difference)) and		
-		(encapsulating encapsulated encapsulation encapsulant mold molded encased encase		
]	encasing))		
23	1		USPAT	2004/08/31 06:06
24	1		USPAT	2004/08/31
25	1		USPAT	06:06 2004/08/31
25			USPAI	06:06
26	1		USPAT	2004/08/31
27	1		TICDAM.	06:06
2 /	1		USPAT	2004/08/31 06:07
28	1		USPAT	2004/08/31
29	1		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	06:07
4.9	1		USPAT	2004/08/31
30	1		USPAT	2004/08/31
31 .	1		USPAT	06:07 2004/08/31
				06:07
32	1		USPAT	2004/08/31 06:07
33	1		USPAT	2004/08/31
34	1		TIG D D W	06:07
	1	•	USPAT	2004/08/31 06:07
35	1		USPAT	2004/08/31 06:08
36	1		USPAT	2004/08/31
37	1		USPAT	06:08 2004/08/31
38	1		IIC D D TT	06:08
30			USPAT	2004/08/31 06:08
39	1		USPAT	2004/08/31
40	1		USPAT	06:08 2004/08/31
			- 	06:08

				10004/00/00
41	1		USPAT	2004/08/31 06:08
42	1		USPAT	2004/08/31 06:08
43	1		USPAT	2004/08/31
44	1		USPAT	06:09 2004/08/31
45	1		USPAT	06:09 2004/08/31
		•		06:09
46	1		USPAT	2004/08/31 06:09
47	1		USPAT	2004/08/31 06:09
48	1		USPAT	2004/08/31 06:09
49	1		USPAT	2004/08/31
50	1		USPAT	06:09 2004/08/31
51	1		USPAT	06:09 2004/08/31
52	1		USPAT	06:09 2004/08/31
53	1			06:10 2004/08/31
	l		USPAT	06:10
54	1		USPAT	2004/08/31 06:10
55	1		USPAT	2004/08/31
56	1		USPAT	2004/08/31
57	1		USPAT	2004/08/31 06:10
58	1		USPAT	2004/08/31 06:10
59	1	,	USPAT	2004/08/31
60	1		USPAT	2004/08/31 06:27
61	1		USPAT	2004/08/31 06:27
62	1		USPAT	2004/08/31 06:27
63	1		USPAT	2004/08/31 06:27
64	1		USPAT	2004/08/31 06:28
65	1		USPAT	2004/08/31
66	1		USPAT	2004/08/31
67	1		USPAT	2004/08/31 06:28
68	1		USPAT	2004/08/31
69	1		USPAT	2004/08/31
70	1		USPAT	06:29 2004/08/31
71	1		USPAT	06:29 2004/08/31 06:29
72	1		USPAT	2004/08/31
73	1	,	USPAT	06:29 2004/08/31
74	1		USPAT	06:30 2004/08/31
75	1		USPAT	06:30 2004/08/31
L	l	· · · · · · · · · · · · · · · · · · ·		06:30

76	1		USPAT	2004/08/31
				06:30
77	1		USPAT	2004/08/31
				06:31
78	1		USPAT	2004/08/31
				06:31
79	1		USPAT	2004/08/31
				06:31
80	1		USPAT	2004/08/31
				06:31
81	1		USPAT	2004/08/31
	, ,			06:31
82	1		USPAT	2004/08/31
83	1		TICDAM.	06:32
03	1		USPAT	2004/08/31
84	1		USPAT	06:32 2004/08/31
04		,	USPAI	06:32
85	1		USPAT	2004/08/31
			USIAI	06:32
86	1		USPAT	2004/08/31
	_		002111	06:32
87	1		USPAT	2004/08/31
				06:32
88	1		USPAT	2004/08/31
				06:32
89	1		USPAT	2004/08/31
	İ			06:32
90	1		USPAT	2004/08/31
				06:32
91	1		USPAT	2004/08/31
				06:32